

Epoxy Resin Systems

no

Plastic Metal

WEICON HP



Pasty | mineral-filled | impact-resistant | adheres to wet and moist surfaces

WEICON HP is a 2-component epoxy resin with longer curing time, enormous impact strength as well as high residual elasticity and abrasion resistance. Due to its high elongation at break and paste-like texture, WEICON HP can be used for repairs, as abrasion protection as well as for lining heavily stressed equipment. The adhesive also shows excellent adhesion to wet and damp surfaces and in underwater applications.

Characteristics

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Base		ероху
Filler		mineral
Texture		pasty
Colour		white
Processing		
Processing temperature		+15°C to +40°C
Component temperature		>3 °C above dew point
relative air humidity		< 85 %
Mixing ratio by weight		100:83
Mixing ratio by volume		100:95
Viscosity of the mixture	at +25 °C	550.000 mPa⋅s
Density of the mixture		1,5 g/cm ³
Consumption	Layer thickness 1.0 mm	1.5 kg/m ²
max. layer thickness	per step	10 mm
Curing		
Pot life	at 20 °C, 500 g batch	30 min.
Additional layer after	(35 % strength)	7 h
Working strength after	(80 % strength)	12 h
Final strength	(100 % strength)	36 h
Shrinkage		0,12 %

Mechanical properties after curing

- measured after curing at		24 h RT + 4 h 60 °C
Tensile strength	DIN EN ISO 527-2	31 MPa
Elongation at break (tensile)	DIN EN ISO 527-2	9,0 %
E-modulus (tensile)	DIN EN ISO 527-2	1800-2000 MPa
Compressive strength	DIN EN ISO 604	65 MPa
Bending strength	DIN EN ISO 178	50 MPa
Impact strength	DIN EN ISO 179-1/1eU	21 kJ/m²
Hardness (Shore D)	DIN ISO 7619	75±3
Adhesive strength	DIN EN ISO 4624	25 MPa
Lap shear strength material thickn.	1,5mm DIN EN 1465	
Steel 1.0338 sandblasted		21 MPa
Stainless steel V2A sandbl	asted	24 MPa
Aluminium sandblasted		14 MPa
Galvanized steel		8 MPa

Thermal parameters

Temperature resistance		-35°C to 160°C
Tg after curing at room temperature	(DSC)	~ +64 °C
Tg after tempering (at 120°C)	(DSC)	+87 °C
Heat deflection resistance	DIN EN ISO 75-2	+65 °C
Thermal conductivity	DIN EN ISO 22007-4	0,4 W/m·K
Heat capacity	DIN EN ISO 22007-4	1,1 J/(g·K)
Electrical parameters		
Resistance	DIN EN 62631-3-1	5,8·10 ¹¹ Ω·m

Instructions for use

magnetic

When using WEICON products, the physical, safety-related, toxicological and ecological data and regulations in our EC safety data sheets (www.weicon.com) must be observed.

Surface pre-treatment

The successful application of WEICON HP depends on the thorough preparation of the surfaces. This is the most important factor for overall success. Dust, dirt, oil, grease, rust and moisture or wetness have a negative impact on the adhesion. Therefore, before processing WEICON HP, the following points must be observed: The areas to be bonded or repaired must be free of any oil, grease, dirt, rust, oxides, paint and other impurities or residues. For cleaning and degreasing, we recommend WEICON Cleaner Spray S.

Smooth and particularly heavily soiled surfaces should additionally be treated by mechanical surface pre-treatment, e.g. by grinding or preferably by blasting. In case of blasting, the surface should be brought to a degree of purity of SA 2 1/2 - "Near White Blast Cleaning" (according to ISO 8501/1-2, NACE, SSPC, SIS). In order to achieve an optimum surface roughness of 75 - 100 µm, angular, disposable blasting media (aluminum oxide, corundum) should be used. The surface quality is negatively influenced by the use of reusable blasting media (slag, glass, quartz), but also by ice blasting. The air for blasting must be dry and oil-free. Metal parts that have come into contact with sea water or other salt solutions should first be rinsed thoroughly with demineralised water and, if possible, left to rest overnight so that all salts can be dissolved from the metal. efore each application of WEICON

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HP, a test for soluble salts should be carried out according to the Bresle method (DIN EN ISO 8502-6).

The maximum amount of soluble salts remaining on the substrate should not exceed 40 mg/m². Heating and repeated blasting of the surface may be necessary to remove all soluble salts and moisture.

After each mechanical pre-treatment, the surface should be cleaned again with WEICON Cleaner Spray S and protected from further contamination until the coating is applied.

Areas where no adhesion to the substrate is desired must be treated with silicone-free mould release agents. For smooth surfaces, we recommend WEICON Mould Release Agent Liquid F 1000 or, for porous surfaces, WEICON Mould Release Agent Wax P 500.

After the surface pre-treatment, WEICON HP should be applied as soon as possible (within one hour) to avoid oxidation, flash rust or new contamination.

Mixing

First, stir the resin. Then mix the resin and hardener together thoroughly and bubble-free for at least four minutes at 20°C (68°F). The included processing spatula or a mechanical mixer, such as a mortar stirrer, can be used for this purpose. With mechanical mixers, a low speed of max. 500 rpm should be used. The components should be stirred until a homogeneous mixture is achieved. The mixing ratio of the two components must be strictly observed, as otherwise, strongly deviating physical values will result (max. deviation +/- 2 %). Only prepare a batch as large as can be processed within the pot life of 30 minutes. The specified pot life refers to a material batch of 500 g and 20°C (68°F) material temperature. Mixing larger quantities or higher processing temperatures will result in faster curing due to the typical reaction heat of epoxy resins.





Application

For processing, we recommend an ambient temperature of 20°C (68°C) at less than 85% relative humidity. The highest adhesive strength is achieved when the parts to be processed are heated to >35°C (>95°F) before application. For a thin pre-coat, work WEICON HP intensively into the surface in crosswise layers using the Contour Spatula Flexy to achieve maximum adhesion. By means of this technique, the epoxy resin penetrates well into all cracks and roughness depths. Afterwards, further applications can be carried out straight away, until the desired layer thickness is reached. Make sure that the epoxy resin is applied evenly and without air bubbles. To fill large gaps or holes, fibreglass, expanded metal or other mechanical fixing materials should be used. Finally, the surface can be smoothed easily with the help of a PE film and a rubber roller.

Curing

Final hardness is reached after 24 hours at 20°C (68°F) at the latest. At lower temperatures, the curing can be accelerated by evenly applying heat up to max. 40°C (104°F), e.g. with a heating pack, hot air blower or fan heater. Higher temperatures shorten the curing time. The following rule of thumb applies: Each increase by +10°C (50°F) above room temperature (20°C/68°F) will decrease the curing time by half. Temperatures below 16°C (61°F) increase the curing time. until at approx. 5°C (41°F) and below, almost no reaction will take place at all.

Storage

Store WEICON HP at room temperature in a dry place. Unopened containers can be stored at temperatures of +18°C to +28°C for at least 36 months after delivery date. Opened containers must be used up within 6 months.

Scope of delivery

Processing Spatula | Contour Spatula Flexy | Instructions for Use | Gloves

Accessories

11202500 15200005 11207400 15207005 10604025	Cleaner Spray S, 500 ml, transparent Cleaner S, 5 L, colourless, transparent Surface Cleaner, 400 ml, transparent Surface Cleaner, 5 L, transparent Mould Release Agent Liquid F 1000, 250 ml, white, milky
10604515 10539115	Mould Release Agent Wax P 500, 150 g
10539115	Repair Stick Multi-Purpose Repair Stick Multi- Purpose, 115 g, vintage white 115 g, vintage white
10850005	Glass Fibre Cloth Tape, 1 PCE, dark grey
10953001	Processing spatula, 1 PCE
10953003	Processing spatula, 1 PCE
15841500	Pump Dispenser WPS 1500, 1,5 L
52000035	Cable Scissors No. 35, 1 PCE
10851010	Processing Kit, 1 PCE

Recommended equipment

Angle grinder blast machine heating pack, hot air blower or fan heater, smoothing trowel, spatula

PE foil 0.2 mm fabric tape paint brush, foam roller rubber roller lint-free cloths

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Conversion table

 $(^{\circ}C \times 1,8) + 32 = ^{\circ}F$ mm/25,4 = inch $\mu m/25, 4 = mil$ $N \times 0,225 = Ib$ $N/mm^2 \times 145 = psi$ $MPa \times 145 = psi$

 $Nm \times 8,851 = Ib \cdot in$ $Nm \times 0.738 = lb \cdot ft Nm$ $x 141,62 = oz \cdot in$ $mPa \cdot s = cP$ $N/cm \times 0,571 = Ib/in$ $kV/mm \times 25,4 = V/mil$

Available sizes:

10390002 WEICON HP, 200 g, white 10390005 WEICON HP, 0,5 kg, white 10390020 WEICON HP, 2 kg, white

	WEICON A	WEICON B	WEICON BR	WEICON C	WEICON F	WEICON F2	WEICON HB 300	WEICON SF	WEICON ST	WEICON TI	WEICON UW	WEICON WR2	WEICON HP	WEICON Ceramic BL	WEICON GL	WEICON GL-S	WEICON Ceramic W	WEICON Ceramic HC 220	WEICON WP	WEICON WR	WEICON CBC
Repair and moulding	х	x	x	x	х	х	x	х	x	х	x	x									
Adhesive				x	х		x		x				x								
Wear protection														х	х	x	х	х	х		
Potting and gap filling	х					х						x								х	х

To the product detail



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Chemical resistance of WEICON Plastic Metals after curing* (Excerpt)

Exhaust fumes	+	Potassium carbonate	+
Acetone	0	Potassium hydroxide 0-20 % (caustic potash)	+
Ethyl ether	+	Milk of lime	+
Ethyl alcohol	0	Carbolic acid	-
Ethylbenzene	-	Creosote oil	-
Alkalis (alkaline substances)	+	Cresylic acid	-
Hydrocarbons, aliphatic (petroleum derivatives)	+	Magnesium hydroxide	+
Formic acid >10 % (methanoic acid)	-	Maleic acid (cis-ethylenedicarboxylic acid)	+
Ammonia anhydrous 25%	+	Methanol (methyl alcohol) <85 %	-
Amyl acetate	+	Mineral oil	+
Amyl alcohol	+	Naphthalene	-
Hydrocarbons, aromatic (benzene, toluene, xylene)	+	Naphthene	-
Barium hydroxide	+	Sodium carbonate (soda)	+
Petrol (92-100 octane)	+	Sodium bicarbonate (sodium hydrogen carbonate)	+
Hydrobromic acid <10 %	+	Sodium chloride (table salt)	+
Butyl acetate	+	Sodium hydroxide >20 % (caustic soda)	0
Butyl alcohol	+	Caustic soda	+
Calcium hydroxide (slaked lime)	+	Heating oil, diesel	+
Chloroacetic acid	-	Oxalic acid <25 % (ethanedioic acid)	+
Chloroform (trichlormethane)	0	Perchloraethylene	0
Chlorosulphuric acid (wet and dry)	-	Kerosene	+
Chlorinated water (swimming pool concentration)	+	Oils, vegetable and animal	+
Hydrochloric acid	+	Phosphoric acid <5%	+
Chromium bath	+	Phthalic acid, phthalic anhydride	+
Chromic acid	+	Crude oil	+
Diesel fuels	+	Nitric acid <5%	0
Mineral oil and mineral oil products	+	Hydrochloric acid <10 %	+
Acetic acid diluted <5%	+	Sulphur dioxide (wet and dry)	+
Ethanol <85 % (ethyl alcohol)	+	Carbon disulphide	+
Greases, oils and waxes	+	Sulphuric acid <5%	0
Hydrofluoric acid diluted	0	White spirit	+
Tannic acid diluted <7%	+	Carbon tetrachloride (tetrachloromethane)	+
Glycerin (trihydroxipropane)	+	Tetralin (tetrahydronaphthalene)	0
Glycol	0	Toluene	-
Humic acid	+	Hydrogen peroxide <30 % (hydrogen superoxide)	+
Impregnating oils	+	Trichloraethylene	0
Potash	+	Xylene	-

^{+ =} resistant 0 = for a limited time - = not resistant *The storage of all WEICON Plastic Metal types was carried out at +20°C chemical temperature.

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